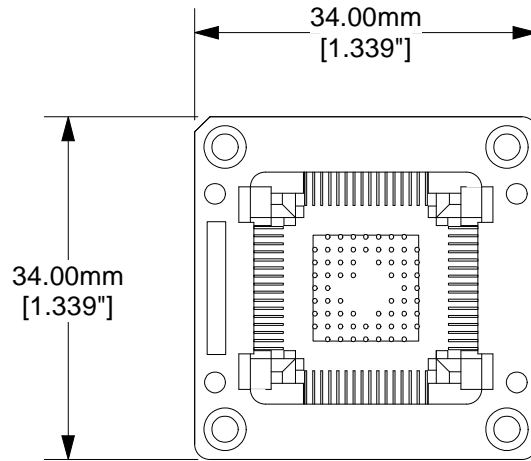
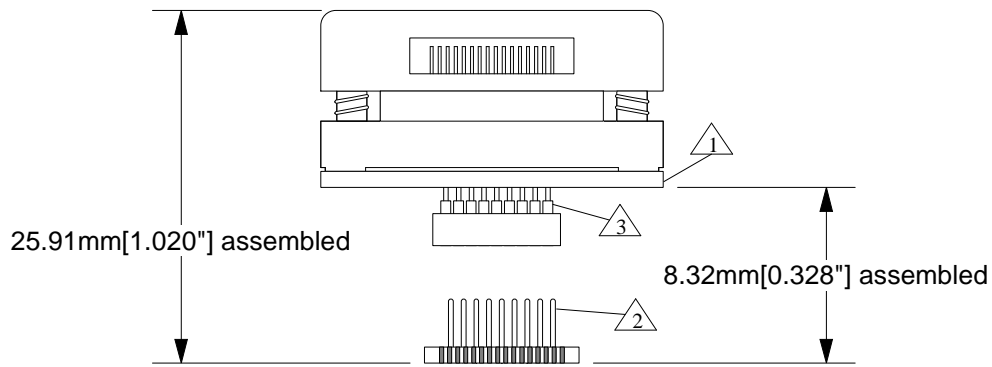


Top View



Side View




- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ " Au over 1.27 μ m [50 μ " Ni (min.).
- ③ Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ " Au over 1.27 μ m [50 μ " Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ " Au over 2.54 μ m [100 μ " Ni (min.).

Description: Carrier Adaptor

64 position (0.8mm pitch) QFP ZIF socket to 64 position surface mountable QFP emulator foot.

The 2 piece adaptor interconnects via a gold plated (1.27mm[0.050"] center) Mini-grid socket interface.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise.

| | | | | |
|---|---|------------------|-----------------------------|--------|
| CA-QFE64SA-L-Z-01 Drawing | | Status: Released | Scale 2:1 | Rev: A |
|  | © 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com | | Drawing: W. Watson | |
| | | | Date: 4/3/00 | |
| | | | File: CA-QFE64SA-L-Z-01 Dwg | |
| | | | Modified: | |